# Unbuffered Inverter NL17SGU04

The NL17SGU04 MiniGate<sup>™</sup> is an advanced high-speed CMOS unbuffered inverter in ultra-small footprint.

The NL17SGU04 input structure provides protection when voltages up to 3.6 V are applied.

#### **Features**

- Wide Operating V<sub>CC</sub> Range: 0.9 V to 3.6 V
- High Speed:  $t_{PD} = 1.9 \text{ ns}$  (Typ) at  $V_{CC} = 3.0 \text{ V}$ ,  $C_L = 15 \text{ pF}$
- Low Power Dissipation:  $I_{CC} = 0.5 \mu A$  (Max) at  $T_A = 25^{\circ}C$
- 3.6 V Overvoltage Tolerant (OVT) Input Pin
- Ultra-Small Packages
- –Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

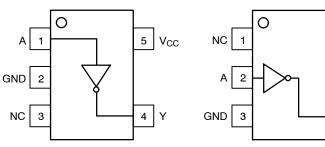


Figure 1. SOT-953 (Top Thru View)

Figure 2. SC-88A (Top View)

1

5 V<sub>CC</sub>

4

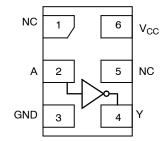


Figure 3. UDFN (Top View)

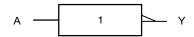


Figure 4. Logic Symbol

#### MARKING DIAGRAMS



SC-88A DF SUFFIX CASE 419A





SOT-953 P5 SUFFIX CASE 527AE





UDFN6 1.45 x 1.0 CASE 517AQ





UDFN6 1.0 x 1.0 CASE 517BX



XX = Specific Device CodeM = Date Code\*= Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT					
	SOT-953 SC-88A UDFN6				
1	Α	NC	NC		
2	GND	А	А		
3	NC	GND	GND		
4	Υ	Υ	Y		
5	V <sub>CC</sub>	V <sub>CC</sub>	NC		
6			V <sub>CC</sub>		

#### **FUNCTION TABLE**

A Input	Y Output
L	Н
Н	L

#### **ORDERING INFORMATION**

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

**Table 1. MAXIMUM RATINGS** 

Symbol	Parameter		Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +4.3	٧
V <sub>IN</sub>	DC Input Voltage		-0.5 to +4.3	٧
V <sub>OUT</sub>	DC Output Voltage Active-Mode (High Tri-State Power-Down Mod	Mode (Note 1)	-0.5 to V <sub>CC</sub> + 0.5 -0.5 to +4.3 -0.5 to +4.3	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < GND	-20	mA
I <sub>OK</sub>	DC Output Diode Current	V <sub>OUT</sub> < GND	-20	mA
I <sub>OUT</sub>	DC Output Source/Sink Current		±20	mA
I <sub>CC or</sub> I <sub>GND</sub>	DC Supply Current Per Supply Pin or Ground Pin		±20	mA
T <sub>STG</sub>	Storage Temperature Range		−65 to +150	°C
T <sub>L</sub>	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature Under Bias		+150	°C
$\theta_{\sf JA}$	Thermal Resistance (Note 2)	SC-88A SOT-953 UDFN6	377 254 154	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°C	SC-88A SOT-953 UDFN6	332 491 812	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating Oxygen I	ndex: 28 to 34	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	j , ,	n Body Model Device Model	2000 1000	V
I <sub>LATCHUP</sub>	Latchup Performance (Note 4)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Applicable to devices with outputs that may be tri-stated.
- Applicable to devices with outputs that may be the stated.
   Measured with minimum pad spacing on an FR4 board, using 10 mm by 1inch, 2 ounce copper trace no air flow per JESD51–7.
   HBM tested to EIA / JESD22–A114–A. CDM tested to JESD22–C101–A. JEDEC recommends that ESD qualification to EIA/JESD22–A115A (Machine Model) be discontinued.
  4. Tested to EIA/JESD78 Class II.

**Table 2. RECOMMENDED OPERATING CONDITIONS** 

Symbol	Parameter		Min	Max	Unit
V <sub>CC</sub>	Positive DC Supply Voltage		0.9	3.6	V
V <sub>IN</sub>	Digital Input Voltage		0	3.6	V
V <sub>ОUТ</sub>	Output Voltage	Active Mode (High or Low State) Tri-State Mode (Note 1) Power Down Mode ( $V_{CC}$ = 0 V)	0 0 0	V <sub>CC</sub> 3.6 3.6	V
T <sub>A</sub>	Operating Free-Air Temperature		-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Transition Rise or Fall Rate	$V_{CC}$ = 3.3 V $\pm$ 0.3 V	0	10	nS/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

#### DC ELECTRICAL CHARACTERISTICS

				1	Γ <sub>A</sub> = 25°C	:		\ = o +125°C	
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	Min	Тур	Max	Min	Max	Unit
V <sub>IH</sub> High-Level Input		0.9	-	$V_{CC}$	-	-	-	V	
	Voltage		1.1 to 1.3	0.8 x V <sub>CC</sub>	_	-	0.8 x V <sub>CC</sub>	-	
			1.4 to 1.6	0.8 x V <sub>CC</sub>	_	-	0.8 x V <sub>CC</sub>	-	
			1.65 to 1.95	0.8 x V <sub>CC</sub>	_	-	0.8 x V <sub>CC</sub>	-	
			2.3 to 2.7	0.8 x V <sub>CC</sub>	_	-	0.8 x V <sub>CC</sub>	-	
			3.0 to 3.6	0.8 x V <sub>CC</sub>	_	-	0.8 x V <sub>CC</sub>	-	
$V_{IL}$	Low-Level Input		0.9	-	GND	-	-	-	V
	Voltage		1.1 to 1.3	-	_	0.2 x V <sub>CC</sub>	-	0.2 x V <sub>CC</sub>	
			1.4 to 1.6	-	_	0.2 x V <sub>CC</sub>	-	0.2 x V <sub>CC</sub>	
			1.65 to 1.95	-	_	0.2 x V <sub>CC</sub>	-	0.2 x V <sub>CC</sub>	
			2.3 to 2.7	-	_	0.2 x V <sub>CC</sub>	-	0.2 x V <sub>CC</sub>	
			3.0 to 3.6	-	_	0.2 x V <sub>CC</sub>	-	0.2 x V <sub>CC</sub>	
V <sub>OH</sub>	V <sub>OH</sub> High-Level Output	$V_{IN} = V_{IH}$ or $V_{IL}$							V
	Voltage	I <sub>OH</sub> = -20 μA	0.9	-	0.75	-	-	-	
		I <sub>OH</sub> = -0.3 mA	1.1 o 1.3	0.75 x V <sub>CC</sub>	-	-	0.75 x V <sub>CC</sub>	-	
		I <sub>OH</sub> = -1.7 mA	1.4 to 1.6	0.75 x V <sub>CC</sub>	_	-	0.75 x V <sub>CC</sub>	-	
		I <sub>OH</sub> = -3.0 mA	1.65 to 1.95	V <sub>CC</sub> – 0.45	-	-	V <sub>CC</sub> - 0.45	-	
		I <sub>OH</sub> = -4.0 mA	2.3 to 2.7	2.0	-	-	2.0	-	
		I <sub>OH</sub> = -8.0 mA	3.0 to 3.6	2.48	-	-	2.48	-	
$V_{OL}$	Low-Level Output	$V_{IN} = V_{IH}$ or $V_{IL}$							V
	Voltage	I <sub>OL</sub> = 20 μA	0.9	-	0.1	-	-	-	
		I <sub>OL</sub> = 0.3 mA	1.1 o 1.3	-	-	0.25 x V <sub>CC</sub>	-	0.25 x V <sub>CC</sub>	
		I <sub>OL</sub> = 1.7 mA	1.4 to 1.6	-	-	0.25 x V <sub>CC</sub>	-	0.25 x V <sub>CC</sub>	
		I <sub>OL</sub> = 3.0 mA	1.65 to 1.95	-	-	0.45	-	0.45	
		I <sub>OL</sub> = 4.0 mA	2.3 to 2.7	-	-	0.4	-	0.4	
	I <sub>OL</sub> = 8.0 mA	2.7 to 3.6	-	-	0.4	-	0.4		
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = GND to 3.6 V	0.9 to 3.6	-	-	±0.1	-	±1.0	μΑ
l <sub>OFF</sub>	Power Off Leakage Current	V <sub>IN</sub> = 0 V to 3.6 V	0	-	_	1.0	-	10.0	μΑ
I <sub>CC</sub>	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	0.9 to 3.6	-	-	1.0	-	10.0	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

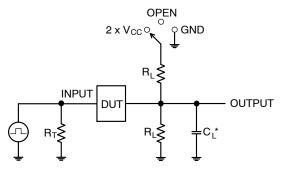
#### **AC ELECTRICAL CHARACTERISTICS**

					T <sub>A</sub> = 25°C	;		, = ) +125°C	
Symbol	Parameter	Test Condition	V <sub>CC</sub> (V)	Min	Тур	Max	Min	Max	Unit
t <sub>PLH</sub> ,	Propagation Delay,	C <sub>L</sub> = 10 pF,	0.9	-	12.7	-	-	-	ns
t <sub>PHL</sub>	A to Y	$R_L = 1 M\Omega$	1.1 to 1.3	-	6.0	9.2	-	12.2	1
			1.4 to 1.6	-	3.2	8.5	-	10.0	1
			1.65 to 1.95	-	2.6	6.2	-	6.7	1
			2.3 to 2.7	-	2.0	3.9	-	4.4	1
			3.0 to 3.6	-	1.7	3.1	-	3.7	1
		C <sub>L</sub> = 15 pF,	0.9	-	13.0	-	-	-	ns
		$R_L = 1 M\Omega$	1.1 to 1.3	-	7.0	9.4	-	12.2	1
			1.4 to 1.6	-	3.5	6.3	-	10.2	
			1.65 to 1.95	-	3.0	5.9	-	7.1	1
			2.3 to 2.7	-	2.3	4.4	-	5.0	1
			3.0 to 3.6	-	1.9	3.4	-	3.9	1
		C <sub>L</sub> = 30 pF,	0.9	-	14.1	-	-	-	ns
		$R_L = 1 M\Omega$	1.1 to 1.3	-	9.0	11.6	-	13.8	1
			1.4 to 1.6	-	6.0	9.1	-	12.9	1
			1.65 to 1.95	-	4.5	8.2	-	9.6	1
			2.3 to 2.7	-	3.2	5.7	-	6.1	1
			3.0 to 3.6	-	2.5	4.4	-	4.8	1
C <sub>IN</sub>	Input Capacitance		0 to 3.6		3	-	-	-	pF
C <sub>O</sub>	Output Capacitance	V <sub>O</sub> = GND	0		3	-	-	-	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 5)	f = 10 MHz	0.9 to 3.6	-	4	-	-	-	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product

performance may not be indicated by the Electrical Characteristics if operated under different conditions.

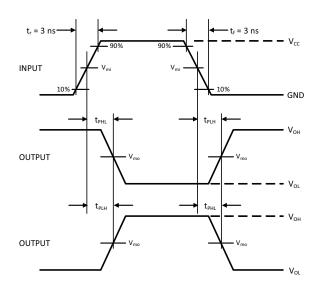
5. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC} \cdot C_{PD}$  is used to determine the no-load dynamic power consumption;  $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \cdot V_{CC}$ .



Test	Switch Position
t <sub>PLH</sub> / t <sub>PHL</sub>	Open
t <sub>PLZ</sub> / t <sub>PZL</sub>	2 x V <sub>CC</sub>
t <sub>PHZ</sub> / t <sub>PZH</sub>	GND

 $C_L$  includes probe and jig capacitance  $R_T$  is  $Z_{OUT}$  of pulse generator (typically 50 W) f = 1 MHz

Figure 5. Test Circuit



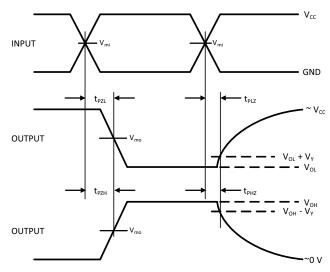


Figure 6. Switching Waveforms

V <sub>CC</sub> , V	V <sub>mi</sub> , V	$V_{mo}$ , $V$	V <sub>Y</sub> , V
0.9	V <sub>CC</sub> /2	V <sub>CC</sub> /2	0.1
1.1 to 1.3	V <sub>CC</sub> /2	V <sub>CC</sub> /2	0.1
1.4 to 1.6	V <sub>CC</sub> /2	V <sub>CC</sub> /2	0.1
1.65 to 1.95	V <sub>CC</sub> /2	V <sub>CC</sub> /2	0.15
2.3 to 2.7	V <sub>CC</sub> /2	V <sub>CC</sub> /2	0.15
3.0 to 3.6	1.5	1.5	0.3

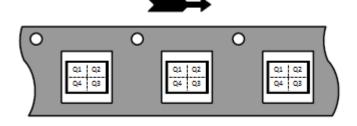
#### **ORDERING INFORMATION**

Device	Package	Marking	Pin 1 Orientation (See below)	Shipping <sup>†</sup>
NL17SGU04DFT2G	SC-88A	AY	Q4	3000 / Tape & Reel
NL17SGU04DFT2G-Q*	SC-88A	AY	Q4	3000 / Tape & Reel
NL17SGU04P5T5G	SOT-953	4	Q2	8000 / Tape & Reel
NL17SGU04MU1TCG	UDFN6, 1.45 x 1.0	3 (Rotated 180° CW)	Q4	3000 / Tape & Reel
NL17SGU04MU3TCG (Contact <b>onsemi</b> )	UDFN6, 1.0 x 1.0	TBD	Q4	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### **PIN 1 ORIENTATION IN TAPE AND REEL**

#### Direction of Feed



MiniGate is a trademark of Semiconductor Components Industries, LLC (SCILLC).

<sup>\*-</sup>Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

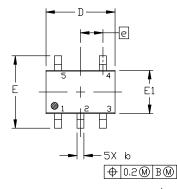
#### **PACKAGE DIMENSIONS**

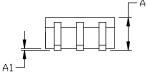
#### SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

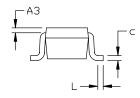
#### NOTES:

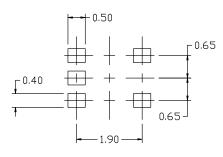
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. 419A-01 DBSDLETE, NEW STANDARD 419A-02
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
  PROTRUSIONS, OR GATE BURRS.MOLD FLASH, PROTRUSIONS,
  OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

DIM	MI	LLIMETE	RS
ויונע	MIN.	N□M.	MAX.
А	0.80	0.95	1.10
A1			0.10
A3	0.20 REF		
b	0.10	0.20	0.30
С	0.10		0.25
D	1.80	2.00	2,20
Е	2.00	2.10	2.20
E1	1.15	1.25	1.35
е	0.65 BSC		
L	0.10	0.15	0.30









## RECOMMENDED MOUNTING FOOTPRINT

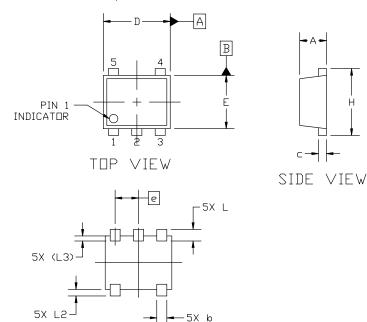
For additional information on our Pb-Free strategy and soldering details, please download the IDN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

#### SOT-953 1.00x0.80x0.37, 0.35P CASE 527AE **ISSUE F**

#### NOTES:

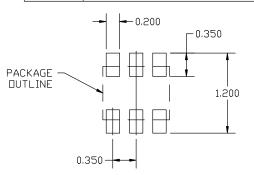
- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
  2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.



BOTTOM VIEW

◆ 0.08 A B

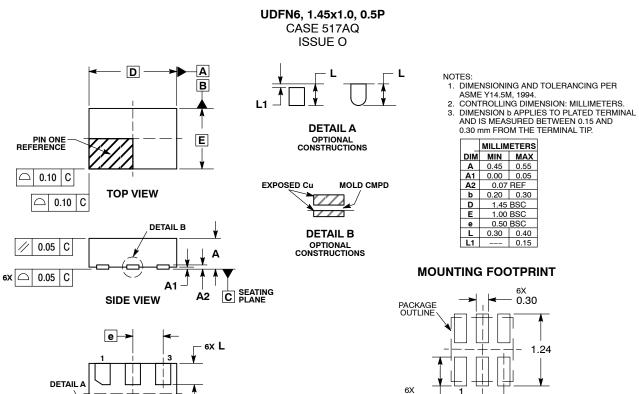
MILLIMETERS					
DIM	MIN	NDM	MAX		
А	0.34	0.37	0.40		
<u>م</u>	0.10	0.15	0.20		
С	0.07	0.12	0.17		
D	0.95	1.00	1.05		
E	0.75	0.80	0.85		
е	(	0.35 BSC	)		
Н	0.95	1.00	1.05		
L	0.125	0.175	0.225		
L2	0.05	0.10	0.15		
L3	0.0	)75 (RE	F)		



#### RECOMMENDED MOUNTING FOOTPRINT

\*For additional information on our Pb-Free strategy and soldering details, please download the  $\Box N$  Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **PACKAGE DIMENSIONS**



0.10

**BOTTOM VIEW** 

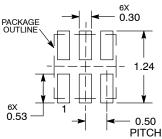
0.05 C

CAB

NOTE 3

	MILLIMETERS				
DIM	MIN	MAX			
Α	0.45	0.55			
A1	0.00	0.05			
A2	0.07 REF				
ь	0.20	0.30			
D	1.45	BSC			
Е	1.00	BSC			
Φ	0.50 BSC				
L	0.30	0.40			
L1		0.15			

#### **MOUNTING FOOTPRINT**

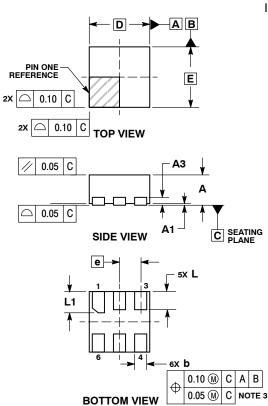


DIMENSIONS: MILLIMETERS

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

#### UDFN6, 1x1, 0.35P CASE 517BX **ISSUE O**

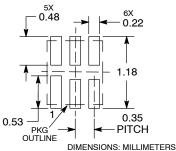


- OTES.

  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
- CONTROLLING DIMENSION: MILLIME TERS DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

_		
	<b>MILLIMETERS</b>	
DIM	MIN	MAX
Α	0.45	0.55
A1	0.00	0.05
АЗ	0.13 REF	
b	0.12	0.22
D	1.00 BSC	
E	1.00 BSC	
е	0.35 BSC	
L	0.25	0.35
L1	0.30	0.40

#### **RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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